WAH LEE INDUSTRIAL CORP.
華立企業股份有限公司
Material Pioneer, Technology Navigator

INVESTOR MEETING
法說簡報

February 2013
2013年2月

TSE Ticker : 3010 TT
http://www.wahlee.com

Company Profile 公司簡介

- Inception : 成立日期 — 10/1/1968
- Listing: 掛牌日期 — 9/22/2002 on TSE(台灣證券交易所)
- Capital: 實收資本額 — NT$ 2,313,901,380
- Market Cap: 市值 — ~USD$315 million
- Core Business: 主要業務 — Leading HI-TECH solutions integrator and raw materials provider for :
  - Computer / Communication
  - Semiconductor
  - PCB /Mother Board
  - FPD
  - Green Energy/Optoelectronics

Sales Offices 國際行銷據點

China
Beijing
Shanghai
Shenzhen
Hong Kong

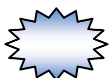
South East Asia
Singapore
Malaysia
Thailand
Philippines

Taipei
Hsinchu
Taichung
Tainan
Kaohsiung

Wah Lee Corp.

USA
San Jose
LA

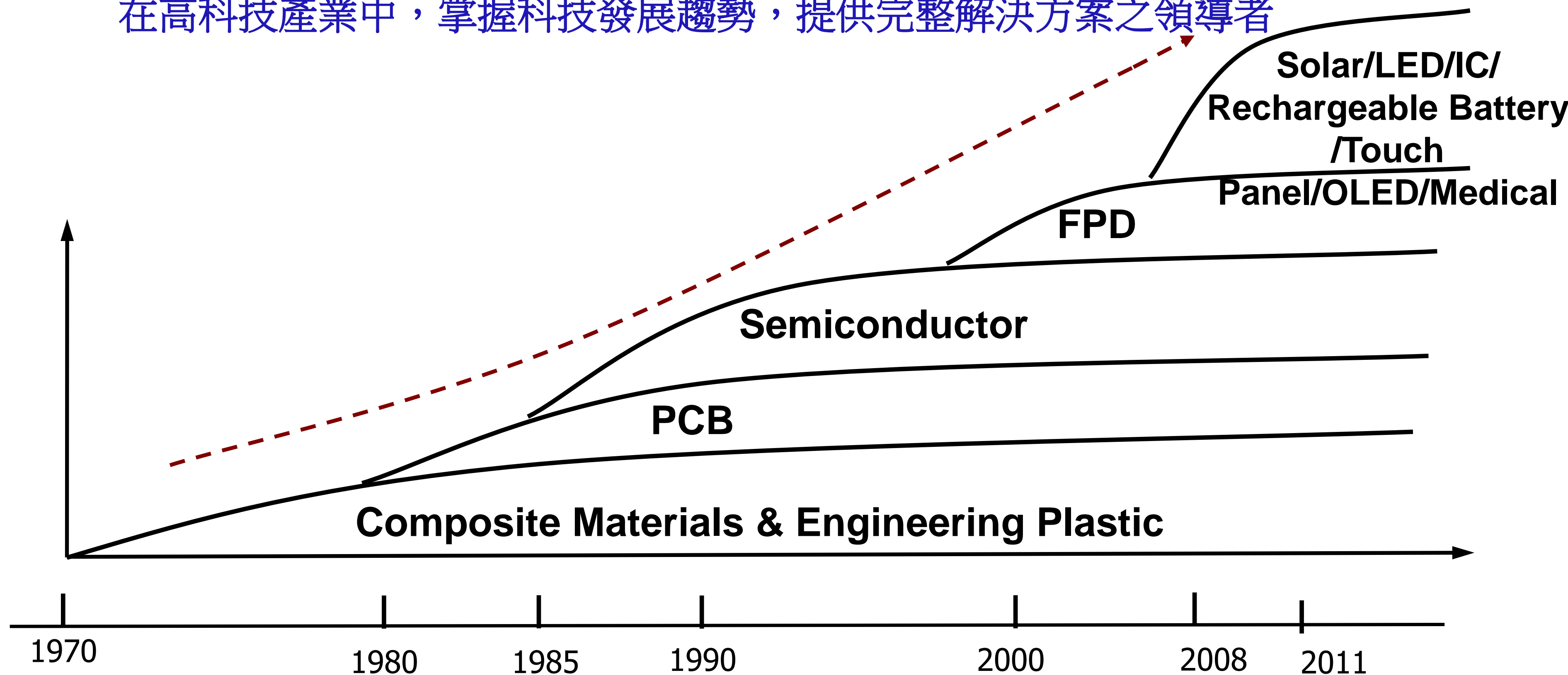
CN 33.4%
Sin. 2.4%
KR 0.2%
TW 64.0%

 Wah Lee Subsidiaries

Wah Lee's Core Competence 華立核心競爭力

I. Leader in foreseeing technology developments and solutions provider of upstream raw materials & equipment in high-tech industries

在高科技產業中，掌握科技發展趨勢，提供完整解決方案之領導者



II. Developing Next Generation Technologies:

投資開發下一代明星產業，如先進顯示技術, 固態照明, 太陽能發電, 電動車等

- **Advanced displays (3D, flexible, transparent…)**
- **Solid state lighting, advanced solar, electrical vehicle related systems…**

Wah Lee's Value Proposition 華立附加價值

Customers Buying Direct
客戶與供應商直接交易

Suppliers 供應商

Customers 客戶

Customers Buying through Wah Lee
華立在供應鏈中提供關鍵附加價值: 一次購足

Suppliers 供應商

FAE engineers 工程師

Warehouse
倉儲系統

Customs Handling進口報關服務

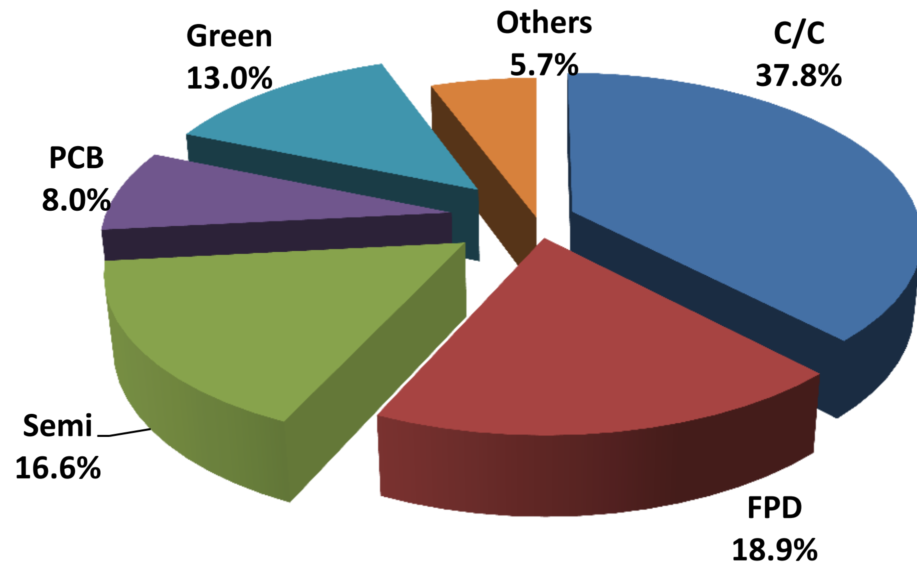
Logistics全方位物流

Customers 客戶

Industry Sales Breakdown
營收產業別資訊

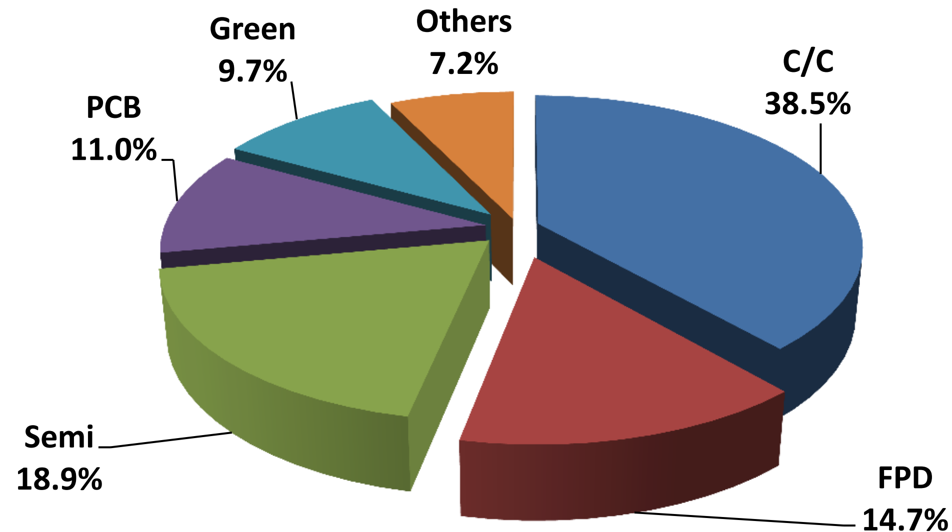
2012/ 01-12(unaudited)

Sales NT$31.5 Billion



2011/ 01-12

Sales NT$31.2 Billion



YTD Consolidated Income 當年至今合併損益

Unit: NT$ million	2012 (Unaudited)	2011 (CPA)	YoY
Net Sales 營收淨額	31,545.3	31,224.5	1%
Gross Profit 銷貨毛利	2,883.5	2,821.8	2%
Gross Margin 毛利率	9.1%	9.0%	0.1%
Op. Expense 營業費用	2,058.5	1,881.9	9%
Op. Profit 營業利益	825.1	939.9	-12%
Non-op. Profit 業外收支	492.1	410.5	20%
L-T investment income 長投收益	409.2	264.3	55%
Disposal gain 處分利益	2.6	37.4	-93%
Others 其他	80.3	108.3	-26%
Pre-tax Profit 稅前利潤	1,317.1	1,350.3	-2%
Net Income 稅後淨利	975.0	952.2	2%
After tax EPS	4.21	4.12	2%

* Consolidated entities include: Wah Lee Taiwan and China Subsidiaries (Raycong, Shanghai YiKang), Wah Lee Japan, Wah Lee Tech(Singapore), and Wah Lee Korea.

*上述合併報表主體，包含華立台灣、大陸子公司(華港香港、上海怡康)，華立日本，華立新加坡，及華立韓國。

Long Term Investments 長期投資分析

Unit: NT$ thousand

Long-term Investments 轉投資事業	Product Lines 主要產品線	Holding % 持有比例 %	2012 Q4 unaudited Earnings Recognized	2012 unaudited Earnings Recognized 長投收益
Chang Wah Electromaterials Inc. 長華電材	Semiconductor Packaging and Testing Materials	**30**	**66,356**	**194,676**
Nagase Wah Lee Plastics 長華塑膠	SABIC Engineering Plastics	**40**	**29,703**	**132,787**
Wah Hong Industrial Corp. 華宏新技	Optical Film, High Performance Plastic Compound, Heat Dissipation Solution, VCM Actuator	**24**	**14,711**	**71,476**
ORC Wah Lee Technology Corp. 華展光電	ORC Exposure Machine and Lamps	**35**	**2,421**	**10,220**
Total			**113,191**	**409,159**

Consolidated Balance Sheet 合併資產負債表

Unit: NT$ million

	2012-12-31 (Unaudited)		2011-12-31 (CPA)			2012-12-31 (Unaudited)		2011-12-31 (CPA)	
Cash & Equiv. 現金	3,402	16.9%	2,471	13.1%	S-T Borrowing 短期借款	3,614	18.0%	3,404	18.0%
A/R 應收帳款	8,531	42.5%	7,793	41.3%	A/P 應付帳款	4,868	24.2%	4,334	22.9%
Inventory 存貨	2,552	12.7%	3,229	17.1%	Other C/L 其他流動負債	817	4.1%	830	4.4%
Other C/A					Current Liab. 流動負債	9,298	46.3%	8,568	45.4%
其他流動資產	529	2.6%	596	3.2%	L-T Liab. 長期負債	1,561	7.8%	1,569	8.3%
Current Assets 流動資產	15,015	74.8%	14,088	74.6%	Other Liab. 其他負債	666	3.3%	644	3.4%
L-T investments 長期投資	3,755	18.7%	3,486	18.5%	Total Liab. 總負債	11,525	57.4%	10,781	57.1%
Fixed Assets 固定資產	974	4.9%	928	4.9%	Capital 股本	2,314	11.5%	2,314	12.2%
Other Assets 其他資產	332	1.7%	388	2.1%	Capital Surplus 資本公積	1,267	6.3%	1,268	6.7%
					Retained Earnings 保留盈餘	4,365	21.7%	3,922	20.8%
					Minority int. & Other Adjust. 少數股權	604	3.0%	605	3.2%
Total Assets 總資產	20,075	100.0%	18,890	100.0%	Total Equities 總股東權益	8,550	42.6%	8,109	42.9%

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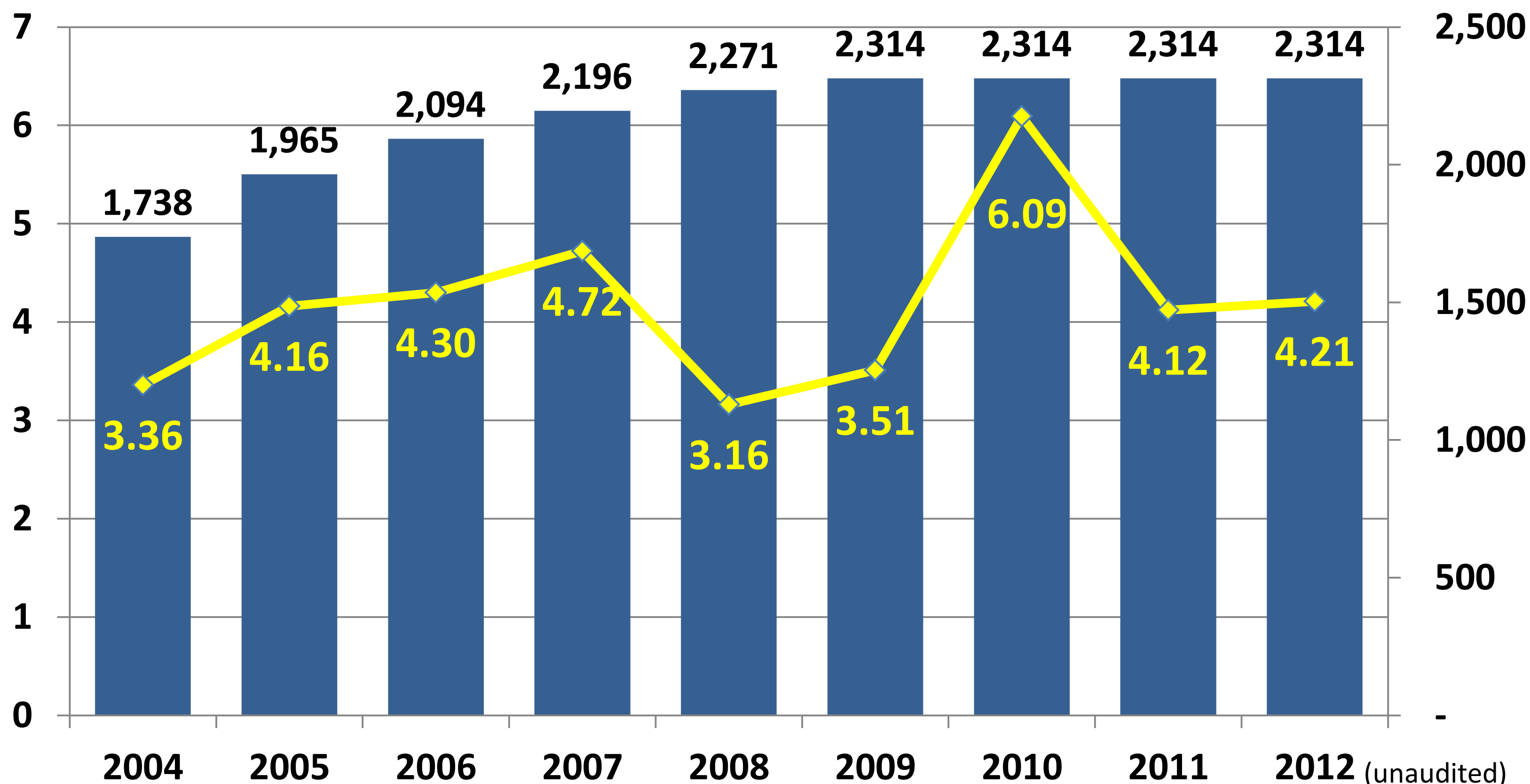
Consolidated Financial Indicators 合併財務比率

	2007	2008	2009	2010	2011	2012 (unaudited)
Current Ratio 流動比率	144.8%	148.6%	171.7%	162.6%	164.4%	161.5%
Quick Ratio 速動比率	98.8%	95.6%	132.4%	115.9%	122.2%	132.0%
Net Debt/Equity 淨負債比率	36.2%	42.3%	9.0%	22.3%	31.0%	20.8%
A/R days 應收帳款天數	84.8	86.3	112.7	87.9	88.9	95.1
Inventory days 存貨天數	53.4	64.8	67.1	47.1	46.2	40.1
A/P days 應付帳款天數	57.9	54.2	81.5	60.8	56.8	58.6
Cash conversion days 現金週轉天數	80.3	96.9	98.3	74.1	78.2	76.6
Operating cash flow (NT$K) 來自營業活動現金流量	243,444	636,700	2,539,747	-389,836	603,187	1,496,248
ROE 股東權益報酬率	18.7%	11.9%	12.3%	19.7%	12.0%	11.7%

After Tax EPS vs Capital Trend
稅後每股盈餘 vs. 資本額



* All EPS prior to 2007 are all deducted by Employee Bonus Expenses to be comparable across the board.

* 2007年及之前各年EPS已經過員工分紅費用之追溯調整，各年EPS具一致之比較基準。

Shareholder Returns Trend 股東投資報酬

Dividend Policy 股利政策

Cash Dividend
現金股息 (NT$)

Payout Ratio
現金股息發放比率

4
3.5
3
2.5
2
1.5
1
0.5
0

70%
60%
50%
40%
30%
20%
10%
0%

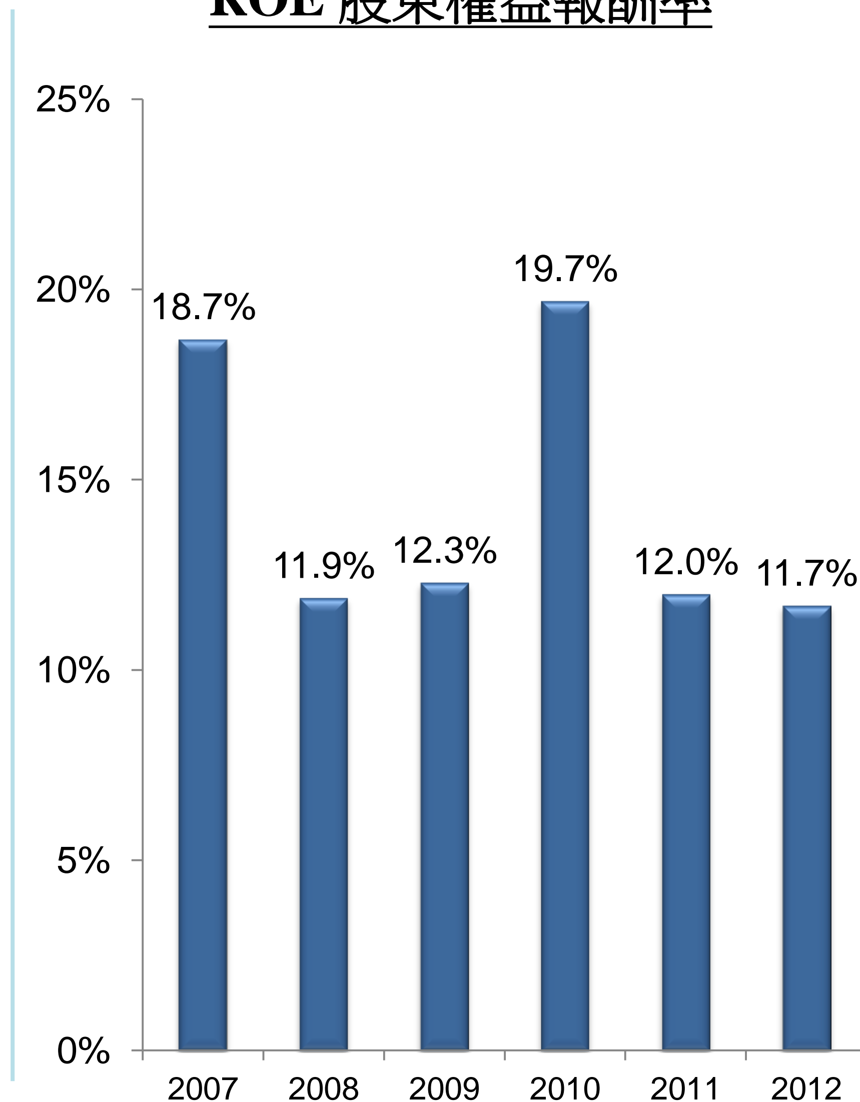
3.8
3.5
1.55
2.3
3.5
2.3

58.2%
52.6%
48.3%
65.5%
57.5%
55.8%

2007 2008 2009 2010 2011 2012

* Dividends are distribution of prior year earnings.

ROE 股東權益報酬率



* ROE of 2012 is unaudited.

Appendix 附錄

2011 Consolidated Income 合併損益

Unit: NT$ million	2011 (CPA)	2010 (CPA)	YoY Growth
Net Sales 營收淨額	31,225	27,023	15.5%
Gross Profit 銷貨毛利	2,822	3,200	-11.8%
Gross Margin 毛利率	9.04%	11.84%	-2.8%
Op. Expense 營業費用	1,882	2,028	-7.2%
Op. Profit 營業利益	940	1,172	-19.9%
Non-op. Profit 業外收支	410	640	-35.9%
L-T investment income 長投收益	264	471	-43.8%
Disposal gain 處分利益	37	100	-62.5%
Others 其他	108	70	55.1%
Pre-tax Profit 稅前利潤	1,350	1,812	-25.5%
Net Income 稅後淨利	952	1,410	-32.5%
After tax EPS	4.12	6.09	-32.3%

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2011 Long Term Investments
2011 長期投資分析

Unit: NT$ thousand

Long-term Investments 轉投資事業	Product Lines 主要產品線	Holding % 持有比例 %	2011 Earnings Recognized 長投收益
Chang Wah Electromaterials Inc. 長華電材	Semiconductor Packaging and Testing Materials	**30**	**14,671**
Nagase Wah Lee Plastics 長華塑膠	SABIC Engineering Plastics	**40**	**161,234**
Wah Hong Industrial Corp. 華宏新技	Optical Film, High Performance Plastic Compound, Heat Dissipation Solution, VCM Actuactor	**24**	**80,243**
ORC Wah Lee Technology Corp. 華展光電	ORC Exposure Machine and Lamps	**35**	**8,182**
Total			**264,330**

Additional dividend income from cost-method investment 成本法股息收益: **14,454**

2011 Consolidated Balance Sheet
2011 合併資產負債表

Unit: NT$ million

	2011-12-31 (CPA)		2010-12-31 (CPA)			2011-12-31 (CPA)		2010-12-31 (CPA)	
Cash & Equiv. 現金	2,471	13.1%	2,039	11.7%	S-T Borrowing 短期借款	3,354	17.8%	2,733	15.6%
A/R 應收帳款	7,793	41.3%	7,303	41.8%	A/P 應付帳款	4,384	23.2%	4,513	25.8%
Inventory 存貨	3,229	17.1%	3,425	19.6%	Other C/L 其他流動負債	831	4.4%	860	4.9%
Other C/A 其他流動資產	596	3.2%	499	2.9%	Current Liab. 流動負債	8,568	45.4%	8,106	46.3%
					L-T Liab. 長期負債	1,569	8.3%	1,041	6.0%
Current Assets 流動資產	14,088	74.6%	13,266	75.8%	Other Liab. 其他負債	644	3.4%	529	3.0%
L-T investments 長期投資	3,486	18.5%	2,957	16.9%	Total Liab. 總負債	10,781	57.1%	9,676	55.3%
Fixed Assets 固定資產	898	4.8%	903	5.2%	Capital 股本	2,314	12.2%	2,314	13.2%
Other Assets 其他資產	418	2.2%	365	2.1%	Capital Surplus 資本公積	1,268	6.7%	1,319	7.5%
					Retained Earnings 保留盈餘	3,922	20.8%	3,780	21.6%
					Minority int. & Other Adjust. 少數股權	499	2.6%	402	2.3%
Total Assets 總資產	18,890	100.0%	17,491	100.0%	Total Equities 總股東權益	8,109	42.9%	7,814	44.7%

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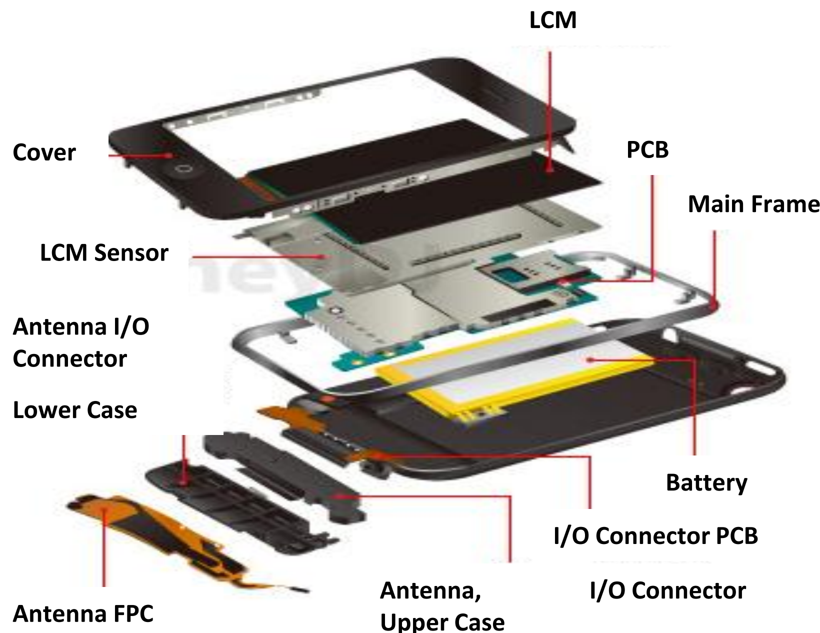
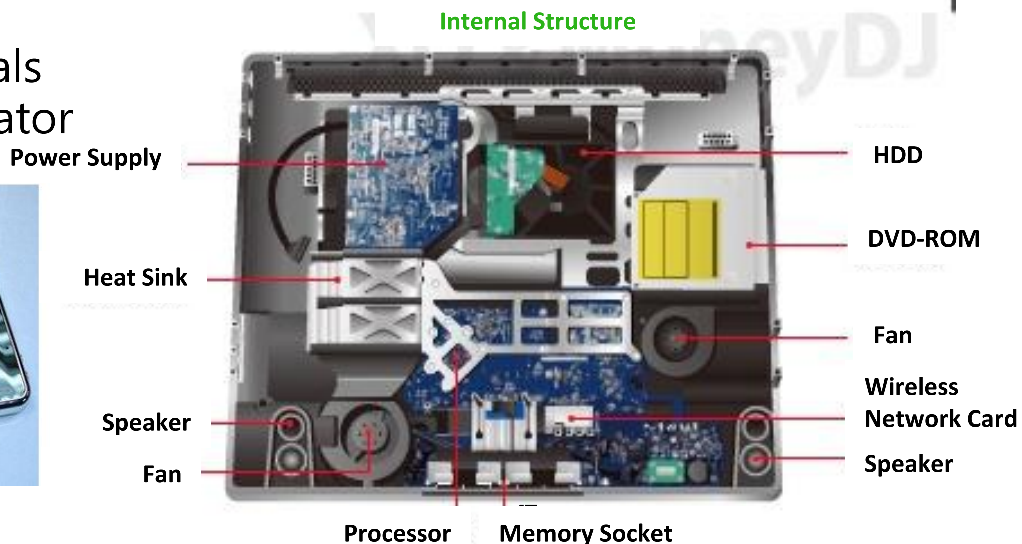
Products in C/C 資訊通訊產品

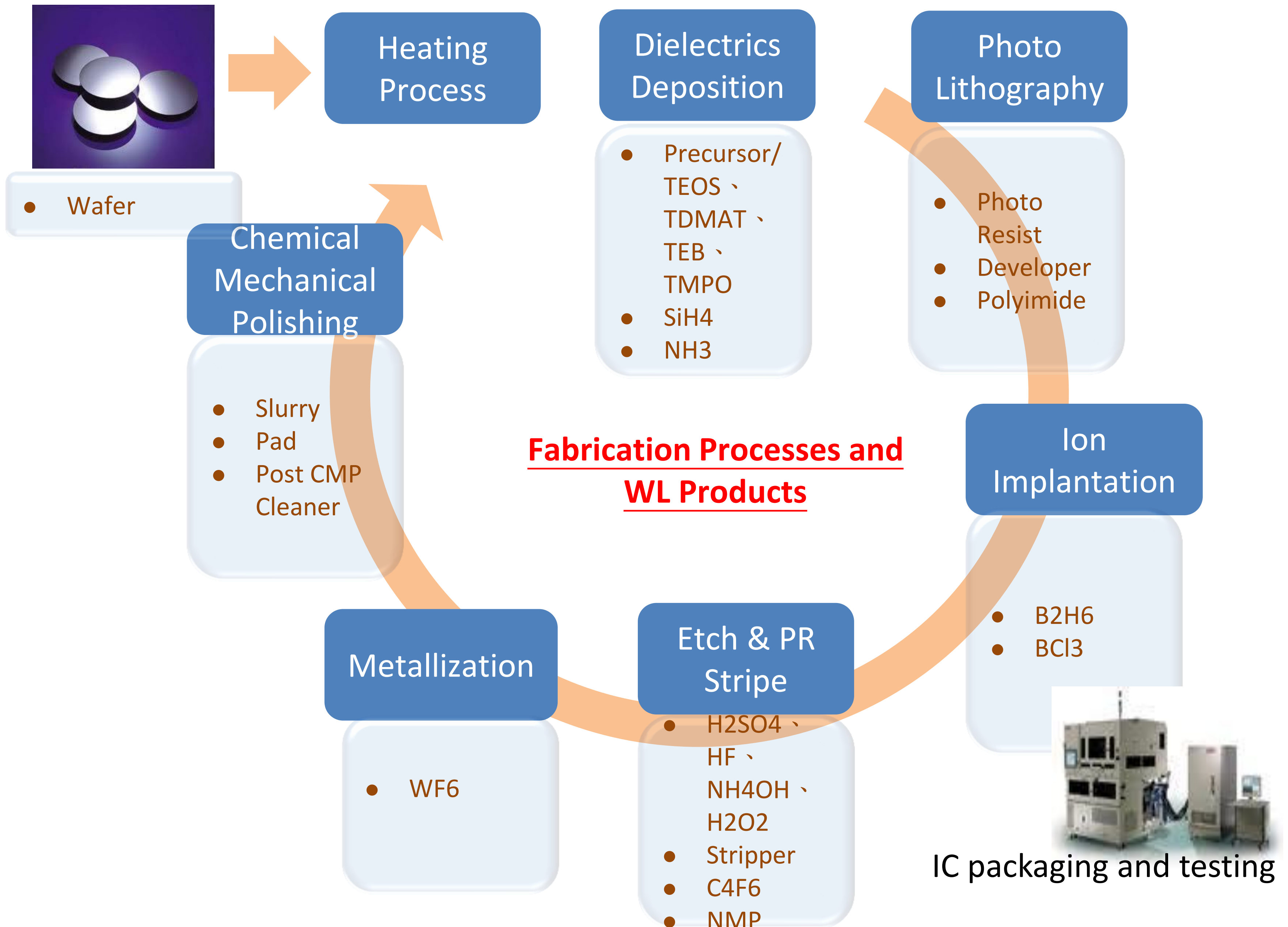
I. High Performance Engineering Plastics
   1. Case : Carbon Fiber、TORAY CFRP、PA
   2. Lens : OKP4、ARTON、HARD COATED SHEET
   3. Insulating Strip、Battery Label :
      PET FILM、PC FILM、PBT FILM
   4. Speaker : PET FILM
   5. Charge Station : Phenolic Mounding Compound
   6. Connector : LCP、PA9T
   7. Reflector : PA9T
   8. Transformer /PFC: Phenolic Mounding Compound
   9. Inverter Bobbin : LCP



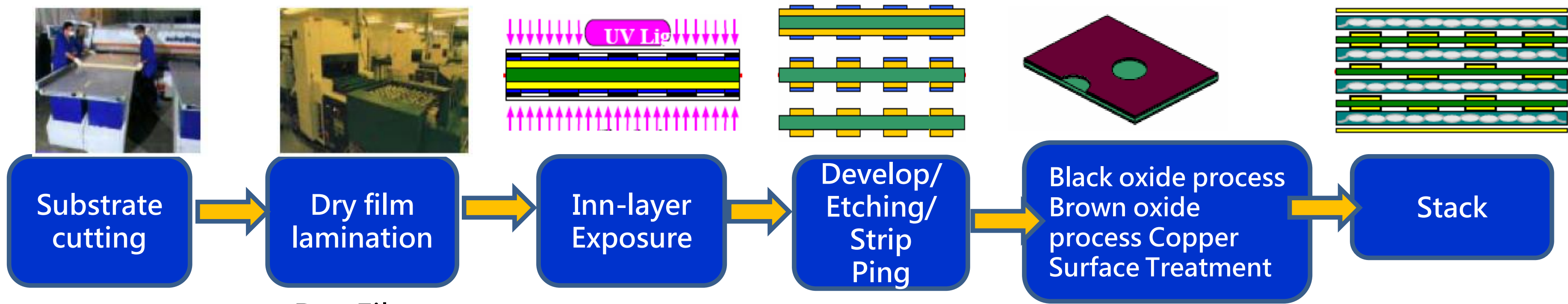
II. Others
   1. Hik@xy Thermal Interface Materials
   2. Camera Module Auto-focus Actuator



Products in Semiconductor Industry 半導體產品

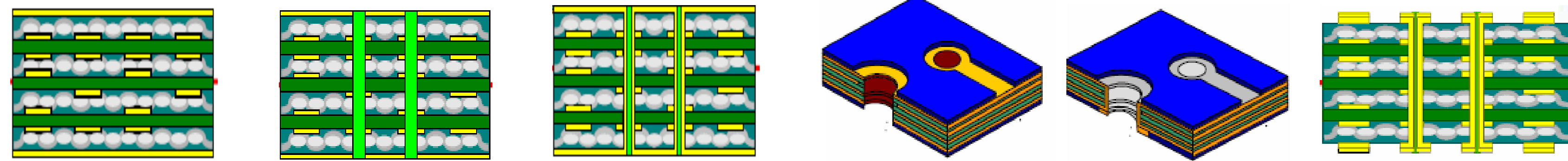


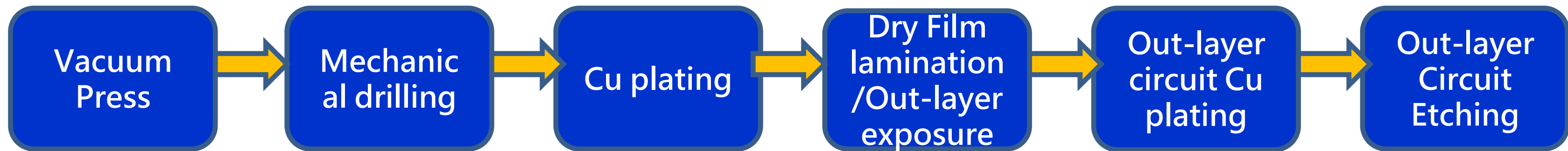
Products in PCB Industry　PCB產業產品



- CCL

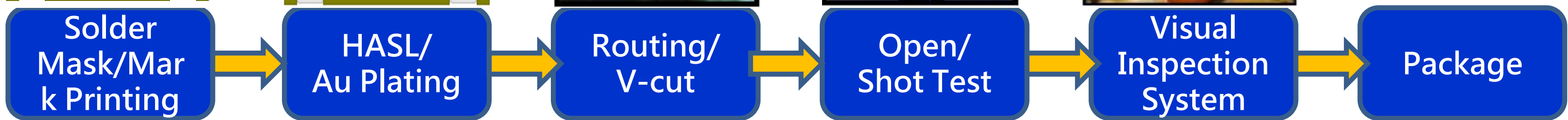
- Dry Film
- Lamination Machine





- Release Film

- Dry Film



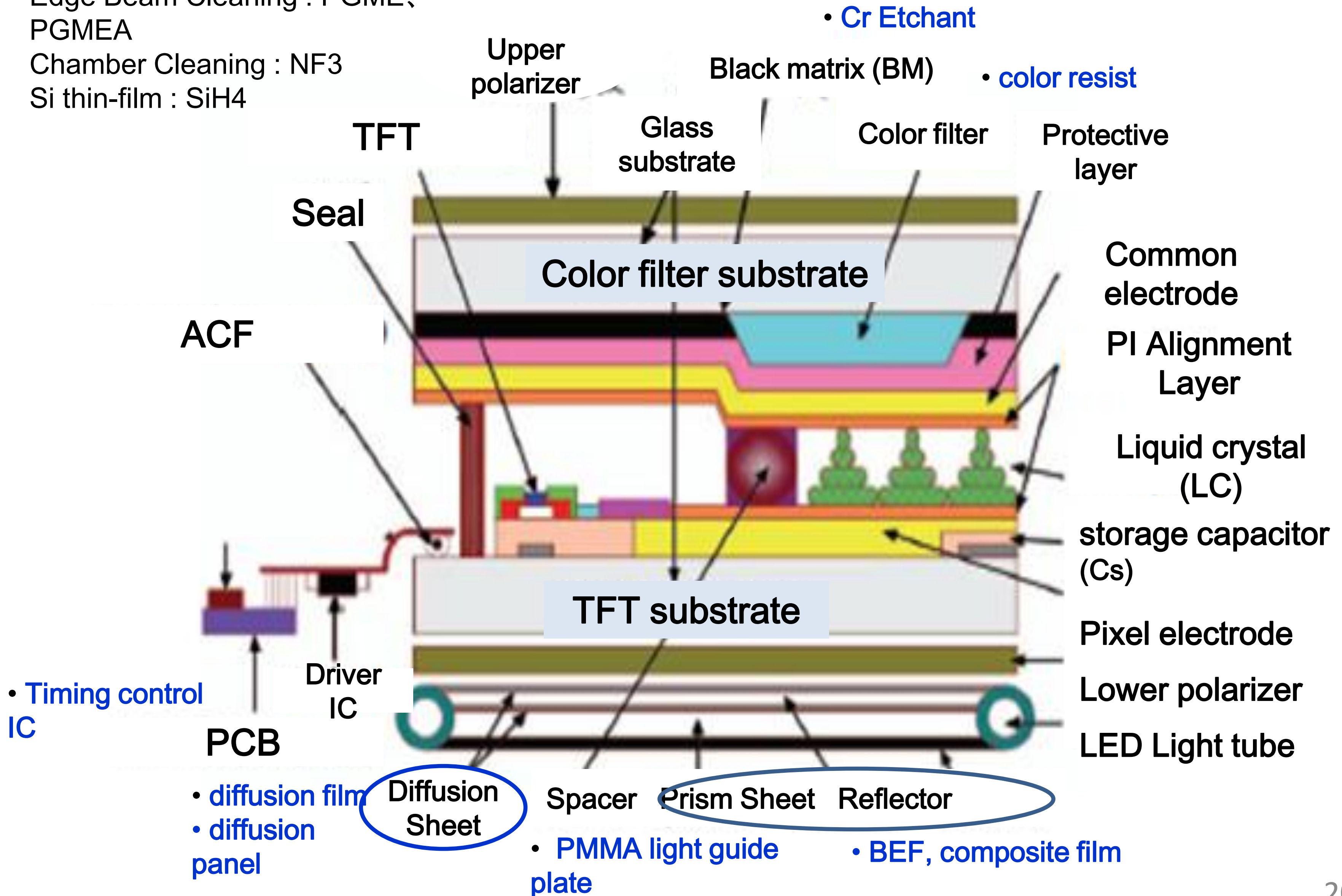
- CNC Router
- Beveling Machine

- AOI
- Screen Visual Inspection

Products in TFT LCD TFT LCD產品

Other chemicals and gas

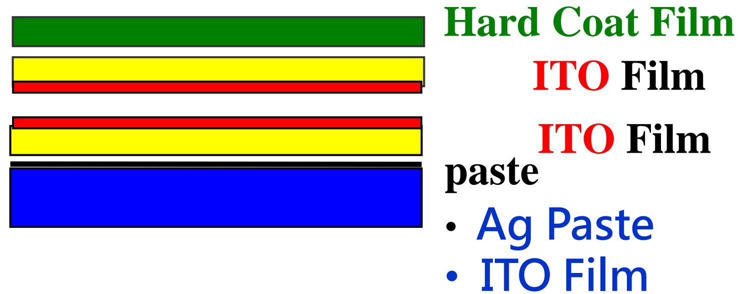
1. Edge Beam Cleaning : PGME、PGMEA
2. Chamber Cleaning : NF3
3. Si thin-film : SiH4



Products in Touch Panel Industry 觸控產品

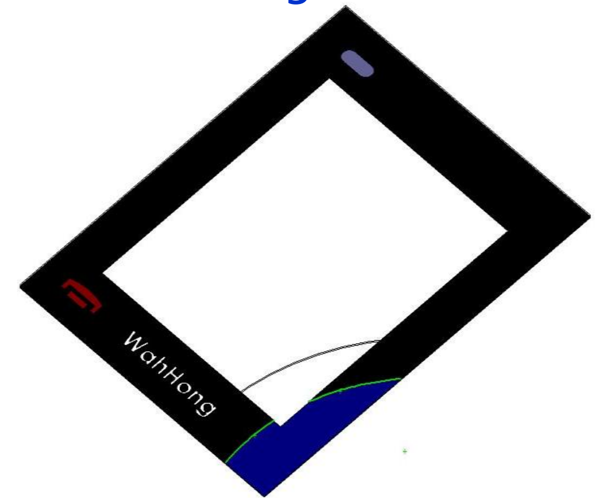
Conductive Silver Paste
Insulating Paste
Printing Ink

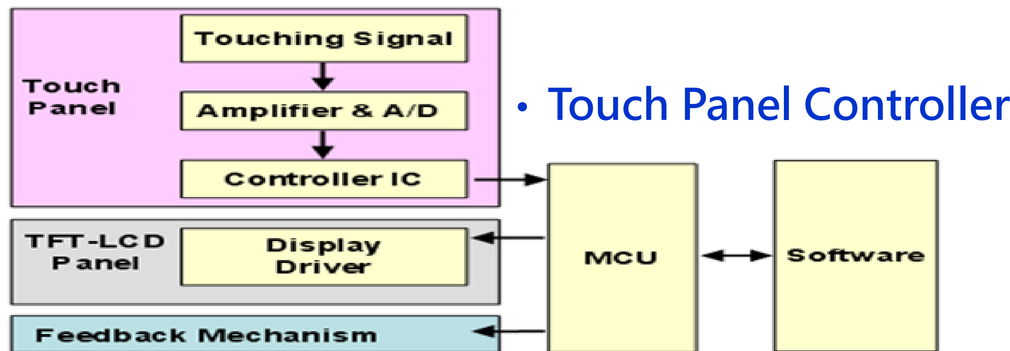
Vertical Structure



- Ag Paste
- ITO Film

- Composite Plate/ Protective Film
- Hard Coated Film/Sheet
- I-con sheet/ Anti-scattering Film



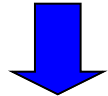


- Touch Panel Controller

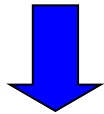
21

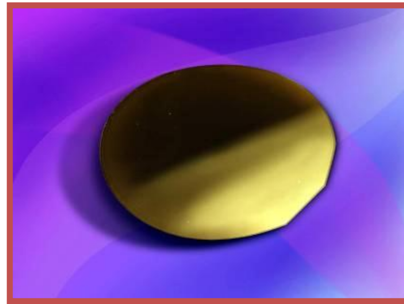
Products in LED Industry LED產品

1. raw materials synthesizing



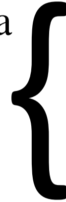
2.distilling/reductive → poly-crystalline





saw slicing to be wafer, and surface polishing

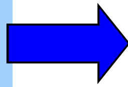
n pole area



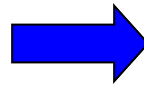
Ti/Al/Ti/Au p pole welded pad
Ni/Au transparent conducting layer
p-GaN epitaxial layer, p =Mg
InGaN/GaN MQW active layer / Ti/Al/Ti/Au n pole welded pad
n-GaN epitaxial layer, n=Si
GaN nucleation layer (30nm)
Sapphire substrate (Al2O3)

- NH3
- TMGa (Tri Methl Ga)
- TMIn (Tri Methl Indium)
- TMAl (Tri Methl Al)
- DuPont Source (DCpMg, Si2H6)

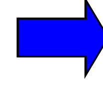
3. single crystal →ingot



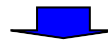
4. wafer/ substrate



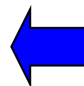
5.epitaxy



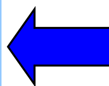
6. epitaxy wafer processing (electrode patterning process)



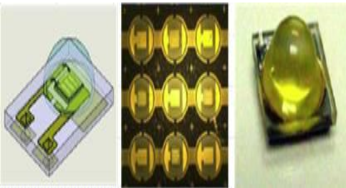
7 . saw slicing to be chip



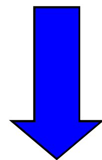
8. packaging



9. component/ module

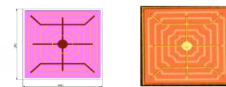


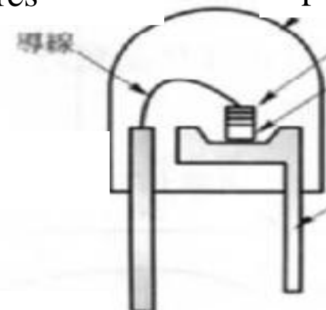
- Emitter
- AC-LED
- Heat spreader
- Optical Film



10. products/semi-manufactured goods

- Street Lamps
- Lighting Equipments

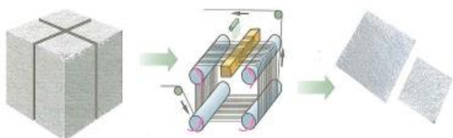




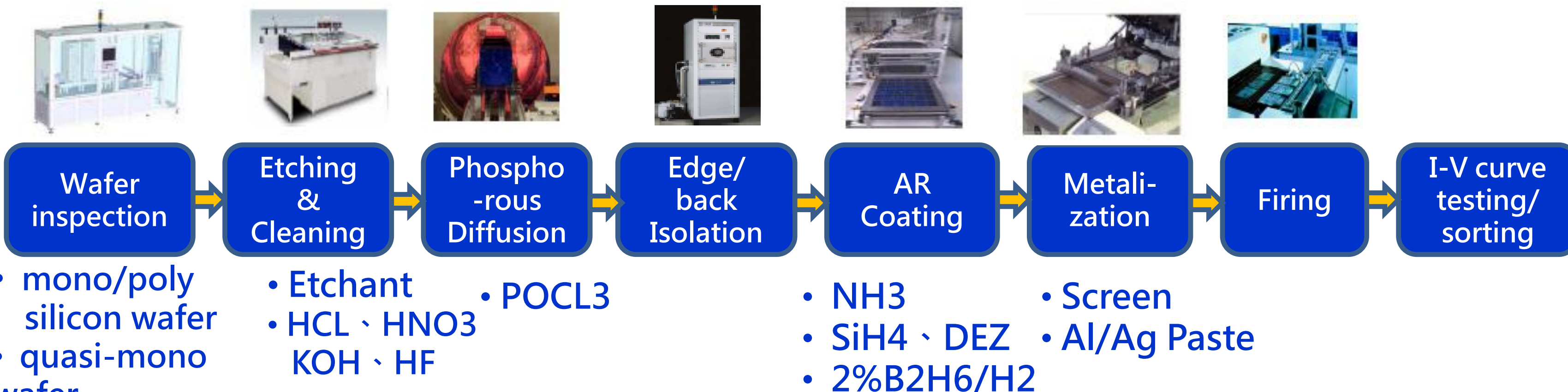
- PA9T
- LCP
- Phosphor
- LED Base Injection Machine
- Packaging Materials
- Die Bonding Silver Paste

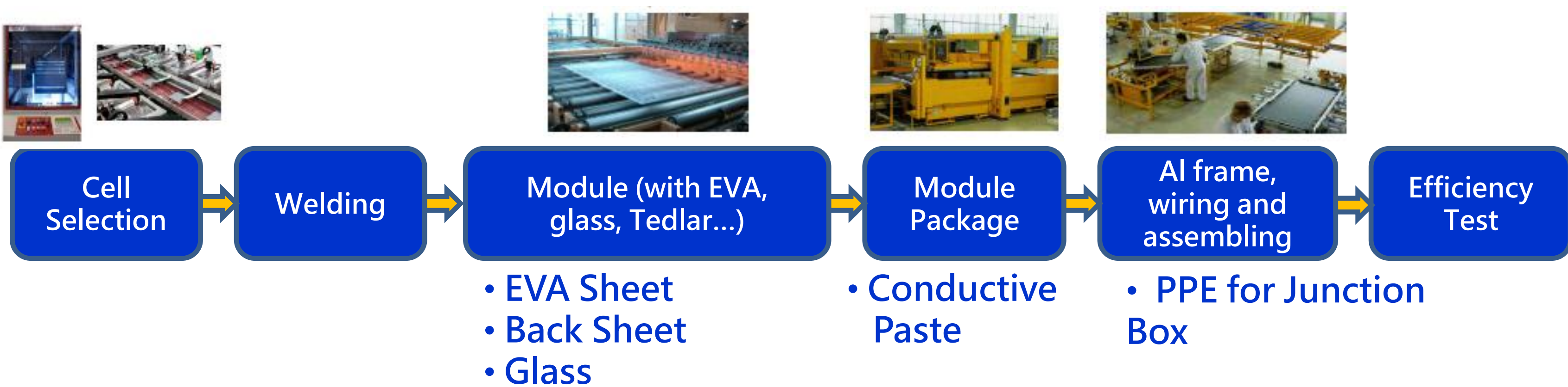
Products in Solar Industry 太陽能產品

- Wire saw
- Diamond saw
- Slurry recycling system



- Chamber Cleaning : NF3





Products in Rechargeable Battery 二次電池產品